

CSP/µBGA Test & Burn-In Socket for Devices up to 13mm Square

FEATURES

- For Test & Burn-In of CSP, µBGA, DSP, LGA, SRAM, DRAM and Flash Devices. Consult factory for QFP applications
- Any pitch device on 0.30mm pitch or higher
- Socket is easily mounted and removed to & from the BIB due to solderless pressure mount compression spring probes which, are accurately located by two molded plastic alignment pins and mounted with four stainless steel screws
- The gold over nickel plated compression spring probes leave very small witness marks on the bottom surface of the device solder balls
- Small overall socket size/profile allows maximum number of sockets per BIB and BIB's per oven, while being operator friendly
- Standard molded socket format can accommodate any device package of 13mm or smaller, by using machined (for small quantities) or custom molded (for large quantities) pressure pads and interposers
- Pressure pad compression spring provides proper force against device and allows for height variations in device thickness
- 4-point crown insures "scrub" on solder oxides
- Signal path during test only 0.077 [1.96]

GENERAL SPECIFICATIONS

- MOLDED SOCKET COMPONENTS: UL 94V-0 Ultem
- MACHINED SOCKET COMPONENTS: UL 94V-0 PEEK or Torlon
- ALL HARDWARE: Stainless Steel
- COMPRESSION SPRING PROBE: heat-treated BeCu
- COMPRESSION SPRING PROBE PLATING: 30μ [0.75μ] min. Au per Mil-G-45204 over 30μ [0.75μ] min. Ni per SAE-AMS-QQ-N-290
- DURABILITY: 500,000 cycles min.
- CONTACT FORCE : 15g per contact on 0.30-0.35mm pitch
 - : 16g per contact on 0.40-0.45mm pitch
 - : 25g per contact on 0.50-0.75mm pitch
 - : 25g per contact on 0.80mm pitch or larger
- OPERATING TEMPERATURE: -55°C [-67°] min. to 150°C [302°] max.
- TYPICAL AVERAGE BURN-IN TEMPERATURE: 150°C max.

MOUNTING CONSIDERATIONS

- See "PCB FOOTPRINT TOP VIEW" for requirements
- REQUIRES: four #2-56 screws and PEM nuts for mounting (not supplied mounting holes size shown may differ depending on PEM nut selected)
- NOTE: Sockets must be handled with care when mounting or removing to/from BIB to avoid damaging sensitive spring contacts
- TEST PCB DIAMETER "G": 0.025 [0.64] (large probe 0.80mm pitch and larger)
 - : 0.015 [0.38] (small probe 0.50-0.75mm pitch)
 - : 0.012 [0.31] (small probe 0.40-0.45mm pitch)
 - : 0.009 [0.23] (small probe 0.30-0.35mm pitch)
- TEST PCB DIAMETER SPRING PROBE PAD PLATING: 30µ [0.75µ] min. Au per MIL-G-45204 over 30µ [0.75µ] min. Ni per SEA-AMS-QQ-N-290. Pad must be the same height as top surface of PCB. Please refer to the Custom Socket Drawing supplied by Aries after receipt of your order for your specific application.



CUSTOMIZATION: In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. **NOTE:** Aries reserves the right to change product general specifications without notice.

ORDERING INFORMATION

Get an Insta-Quote

A detailed device drawing must be sent to Aries to quote and design a socket.

See Data Sheet...

23021 μBGA up to 6.5mm 23018 μBGA up to 27mm 23018-APP w/Adj Pressure Pad 23019 μBGA up to 40mm 23020 μBGA up to 55mm

24013 RF up to 6.5mm 24008 RF up to 13mm 24009 RF up to 27mm 24009-APP w/Adj Pressure Pad 24011 RF up to 40mm 24012 RF up to 55mm

23016 CSP/BallNest[™] Hybrid 24010 RF Machined Socket 23022 Kelvin Test Socket



Bristol, PA 19007-6810 USA TEL (215) 781-9956 • FAX (215) 781-9845 WWW.ARIESELEC.COM • INFO@ARIESELEC.COM





23017 1 of 2 Rev. AA

PRINTOUTS OF THIS DOCUMENT MAY BE OUT OF DATE AND SHOULD BE CONSIDERED UNCONTROLLED





23017 2 of 2 Rev. AA

PRINTOUTS OF THIS DOCUMENT MAY BE OUT OF DATE AND SHOULD BE CONSIDERED UNCONTROLLED